

AMENDMENTS TO THE SPECIFICATION:

Please replace the previously-filed Abstract of the Disclosure with the accompanying substitute Abstract of the Disclosure provided on a separate sheet in the Appendix.

Page 2, replace paragraph [0007] beginning on line 17 with the following amended paragraph:

-- It is difficult for a cured product composed mainly of an epoxy compound and a curing agent therefor to satisfy all the required performance properties. It has been desired to provide a curing composition capable of forming a cured product with a low dielectric constant particularly in the [[filed]] field of laminates having seen remarkable development in fine processing technology.--

Page 2, replace paragraph [0009] beginning on line 27, with the following amended paragraph:

--The present invention ~~(the invention according to claim 1)~~ accomplishes the above object by providing a vinyl ether curing composition composed of a polyfunctional vinyl ether compound and a polyhydric phenol compound.--

Page 3, replace paragraph [0010] beginning on line 2, with the following amended paragraph:

--The invention ~~according to claim 2~~ provides the vinyl ether curing composition ~~of claim 1~~ which contains 100 parts by weight of the polyfunctional vinyl ether compound, 30 to 200 parts by weight of the polyhydric phenol compound, 10 to 3000

parts by weight of a filler, and 10 to 200 parts by weight of a flame retardant.--

Page 3, replace paragraph [0011] beginning on line 7, with the following amended paragraph:

--The invention ~~according to claim 3~~ provides the vinyl ether curing composition ~~of claim 1 or 2~~, wherein the polyfunctional vinyl ether compound is a tetra- or higher functional vinyl ether compound.--

Page 3, replace paragraph [0012] beginning on line 11, with the following amended paragraph:

--The invention ~~according to claim 4~~ provides the vinyl ether curing composition ~~of any one of claims 1 to 3~~, wherein the polyhydric phenol compound is a phenol resin represented by general formula (I):--

Page 3, replace paragraph [0014] beginning on line 19, with the following amended paragraph:

--The invention ~~according to claim 5~~ provides the vinyl ether curing composition ~~of any one of claims 1 to 4~~ which contains 10 to 1000 parts by weight of silica as the filler per 100 parts by weight of the total of the polyfunctional vinyl ether compound and the polyhydric phenol compound.--

Page 3, replace paragraph [0015] beginning on line 24, with the following amended paragraph:

--The invention ~~according to claim 6~~ provides the vinyl ether curing composition ~~according to any one of claims 1 to 5~~ which contains 10 to 50 parts by weight of a phosphorus-based flame retardant as the flame retardant per 100 parts by weight of the total of the polyfunctional vinyl ether compound and the polyhydric phenol compound.--

Page 4, replace [0016] beginning on line 4, with the following amended paragraph:

--The invention ~~according to claim 7~~ provides the vinyl ether curing composition ~~of claim 6~~, wherein the phosphorus-based flame retardant is a compound represented by formula (II):--

Page 4, replace paragraph [0018] beginning on line 11, with the following amended paragraph:

--The invention ~~according to claim 8~~ provides the vinyl ether curing composition ~~according to any one of claims 1 to 7~~ which contains a polyepoxy compound.--

Page 4, replace [0019] beginning on line 14, with the following amended paragraph:

--The invention ~~according to claim 9~~ provides a prepreg formed by using the vinyl ether curing composition ~~according to any one of claims 1 to 8~~.--

Page 4, replace paragraph [0021] beginning on line 23, with the following amended paragraph:

--The present invention will be described in detail.
The term "the (present) invention" as used herein means one or
more embodiments of the invention according to claims 1 to 8.--